

# A unique solution for testing MEMS Inertial Sensors

## All-in-one system for testing, calibration, final inspection and packaging

- Architecture isolates the test of MEMS from outside noise and vibration, significantly increasing test accuracy and output
- No special requirements on the production floor for either the handling system or the tester
- Up to 3,060 signal lines (shielded)
- High parallel testing of up to 250 devices simultaneously
- Sense+™ system features all the capabilities of a turret automation platform
- g-sense™ test solution is independent of the Sense+™ system with maximum freedom of movement
- NV-Core™ Inspection System provides full final inspection and unit-level traceability from wafer input to tape & reel output
- DI-Core™ Data Intelligence System providing real-time equipment monitoring and data analytics for increased productivity

# Sense+ with g-sense MEMS inertial test solution



Sense+ system with  
*g-sense* test solution  
High-volume production



*g-sense* test solution can  
be used standalone  
Engineering

## Significant improvement in test accuracy and parallelism

- Sense+ system can operate on a standard noisy test floor with no need to stop handling for idle or silent mode during test
- Two dynamic axis with  $270^\circ$  ( $-90^\circ$  to  $180^\circ$ ) for best possible test flow
- Accuracy
  - Stable angular velocity: Yaw rate  $\pm 0.005\%$
  - High position accuracy: Axes  $< \pm 0.1^\circ$  (typical  $0.05^\circ$ )
  - Noise level on DUT position:  $< 10$  Hz: typical  $270 \mu\text{g rms}$
- 32-position turret test and scan complete finishing solution with full 6-sided optical inspection
- Solutions for different packages across different loading media, wafer, bowl, and tray testing
- Flexibility to reconfigure the Sense+ automation platform to test different sensors; inertial, microphone, microphone-loudspeaker<sup>(1)</sup>, pressure<sup>(1)</sup>, and magnet<sup>(1)</sup>
- *g-sense* test solution can be mechanically de-coupled from the Sense+ system for use as a standalone unit for engineering in a lab environment or low-volume manufacturing

(1) Roadmap development

# NV-Core™

## Inspection System



- Full 6-sided post testing die inspection
- Micro-scale defect detection down to 50 µm
- Vision assisted accurate die placement
- Completed unit-level traceability from wafer input to tape & reel output
- Pre-tape pocket integrity, in-tape device quality, and post-sealing quality inspection capabilities



# DI-Core™

## Data Intelligence System

- Real-time equipment monitoring and management
- Preventative maintenance
- Central recipe management
- Optimized yield and defect detection through real-time Artificial Intelligence inspection
- Knowledge database and unified reports



All specifications are subject to change without notification and are for reference only. For detailed performance specifications, please contact Cohu.

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[www.cohu.com/mems-inertial-test](http://www.cohu.com/mems-inertial-test)

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